

Solid State Relay OCMOS FET

PS7141E-1A, PS7141EL-1A

6-PIN DIP, 400V BREAK DOWN VOLTAGE 1-ch Optical Coupled MOS FET

DESCRIPTION

The PS7141E-1A and PS7141EL-1A are solid state relays containing GaAs LEDs on the light emitting side (input side) and MOS FETs on the output side.

They are suitable for analog signal control because of their low offset and high linearity.

The PS7141EL-1A has a surface mount type lead.

FEATURES

- 1 channel type (1 a output)
- · Designed for AC/DC switching line changer
- Small package (6-pin DIP)
- · Low offset voltage
- PS7141EL-1A: Surface mount type
- · Ordering number of taping product: PS7141EL-1A-E3, E4
- · Safety standards
 - UL approved: File No. E72422BSI approved: No. 8806/8807

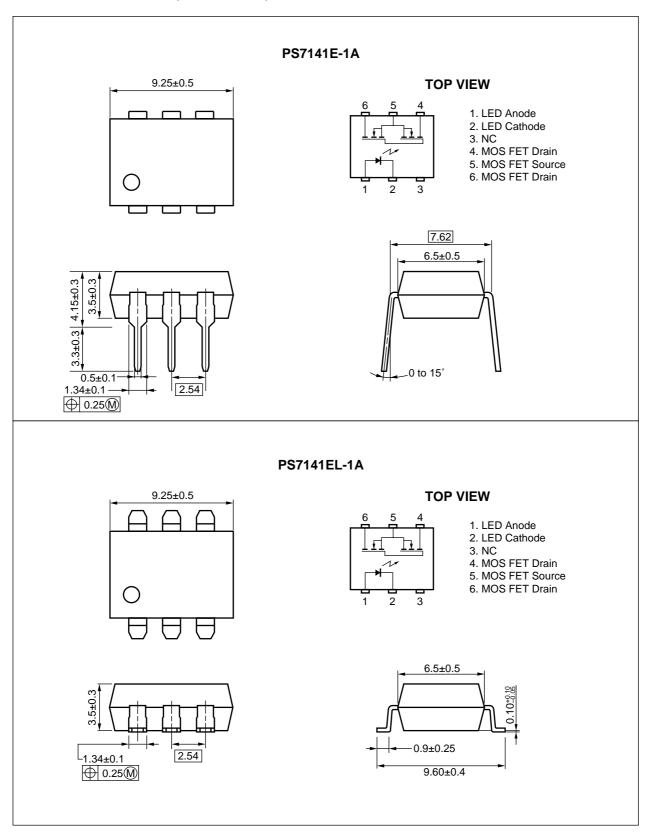
APPLICATIONS

- · Exchange equipment
- · Measurement equipment
- FA/OA equipment

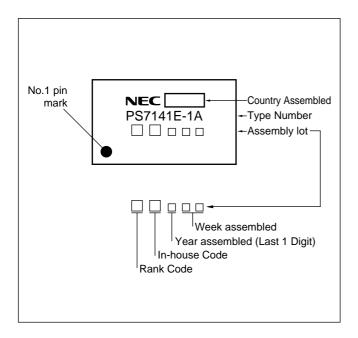
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Not all devices/types available in every country. Please check with local NEC Compound Semiconductor Devices representative for availability and additional information.

PACKAGE DIMENSIONS (in millimeters)



MARKING EXAMPLE



ORDERING INFORMATION

Part Number	Package	Packing Style	Application Part Number ^⁴
PS7141E-1A	6-pin DIP	Magazine case 50 pcs	PS7141E-1A
PS7141EL-1A			PS7141EL-1A
PS7141EL-1A-E3		Embossed Tape 1 000 pcs/reel	
PS7141EL-1A-E4			

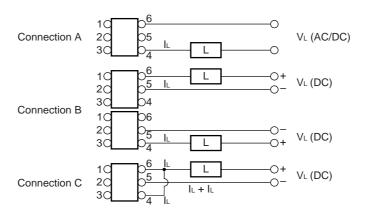
^{*1} For the application of the Safety Standard, following part number should be used.

ABSOLUTE MAXIMUM RATINGS (TA = 25°C, unless otherwise specified)

Parameter			Symbol	Ratings	Unit
Diode	Forward Current (DC)		lF	50	mA
	Reverse Voltage		VR	5.0	٧
	Power Dissipation		PD	50	mW
	Peak Forward Current [™]		IFP	1	Α
MOS FET	Break Down Voltage		VL	400	٧
	Continuous	Connection A	l _L	120	mA
	Load Current ^{*2}	Connection B		150	
		Connection C		250	
	Pulse Load Current ⁻³ (AC/DC Connection)		ILP	240	mA
Power Dissipation		Po	560	mW	
Isolation Voltage *4		BV	1 500	Vr.m.s.	
Total Power Dissipation		Рт	610	mW	
Operating Ambient Temperature		TA	-40 to +85	°C	
Storage Temperature			T _{stg}	-40 to +100	°C

^{*1} PW = 100 μ s, Duty Cycle = 1%

^{*2} Conditions: IF \geq 5 mA. The following types of load connections are available.



^{*3} PW = 100 ms, 1 shot

^{*4} AC voltage for 1 minute at T_A = 25°C, RH = 60% between input and output

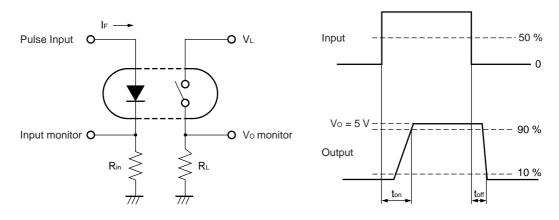
RECOMMENDED OPERATING CONDITIONS (TA = 25°C)

Parameter	Symbol	MIN.	TYP.	MAX.	Unit	
LED Operating Current	lF	5	10	20	mA	
LED Off Voltage	VF	0		0.5	V	

ELECTRICAL CHARACTERISTICS (TA = 25°C)

	Parameter	Symbol	Conditions	MIN.	TYP.	MAX.	Unit
Diode Forward Voltage		VF	IF = 10 mA		1.2	1.4	V
	Reverse Current	lr	V _R = 5 V			5.0	μΑ
MOS FET	Off-state Leakage Current	ILoff	V _D = 400 V		0.01	1.0	μΑ
	Output Capacitance	Cout	V _D = 0 V, f = 1 MHz		36		pF
Coupled	LED On-state Current	I Fon	IL = 120 mA			5.0	mA
	On-state Resistance	R _{on1}	IF = 10 mA, IL = 10 mA		36	50	Ω
		Ron2	$I_F = 10 \text{ mA}, I_L = 120 \text{ mA}, t \le 10 \text{ ms}$		25	35	
	Turn-on Time*1,2	ton	If = 10 mA, Vo = 5 V, RL = 1.5 k Ω ,		0.5	1.0	ms
	Turn-off Time*1,2	toff	PW ≥ 10 ms		0.07	0.2	
	Isolation Resistance	R _{I-O}	Vi-o = 1.0 kVpc	10°			Ω
	Isolation Capacitance	C _{I-O}	V = 0 V, f = 1 MHz		1.1		pF

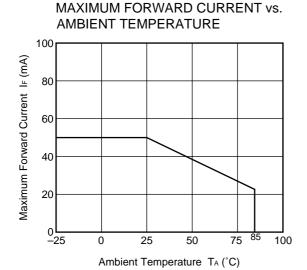
*1 Test Circuit for Switching Time



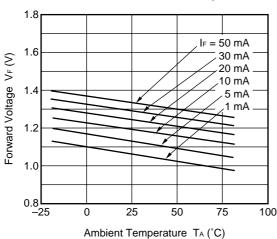
*2 The turn-on time and turn-off time are specified as input-pulse width ≥ 10 ms.

Be aware that when the device operates with an input-pulse width of under 10 ms, the turn-on time and turn-off time will increase.

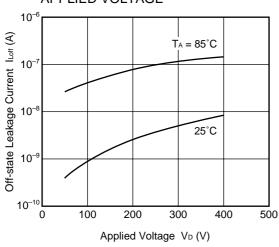
TYPICAL CHARACTERISTICS (TA = 25°C, unless otherwise specified)





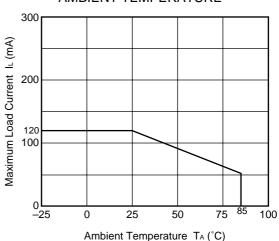


OFF-STATE LEAKAGE CURRENT vs. APPLIED VOLTAGE

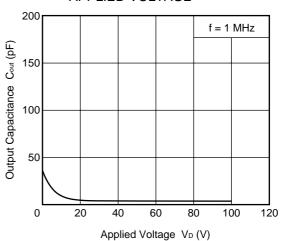


Remark The graphs indicate nominal characteristics.

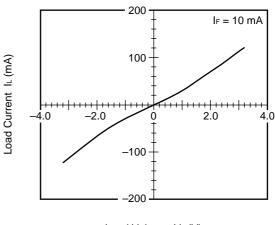




OUTPUT CAPACITANCE vs. APPLIED VOLTAGE

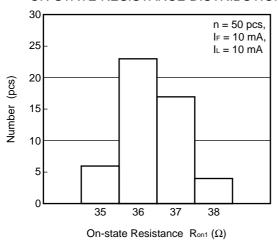


LOAD CURRENT vs. LOAD VOLTAGE

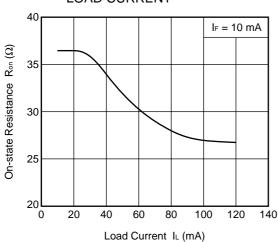


Load Voltage V_L (V)

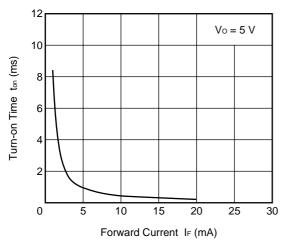
ON-STATE RESISTANCE DISTRIBUTION



ON-STATE RESISTANCE vs. LOAD CURRENT

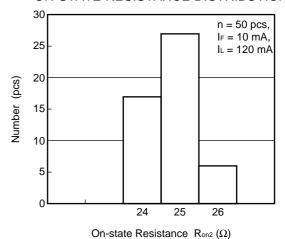


TURN-ON TIME vs. FORWARD CURRENT

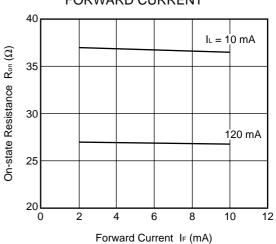


Remark The graphs indicate nominal characteristics.

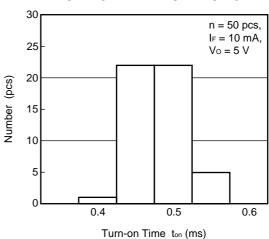
ON-STATE RESISTANCE DISTRIBUTION



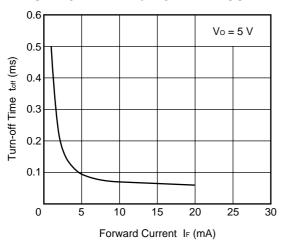
ON-STATE RESISTANCE vs. FORWARD CURRENT



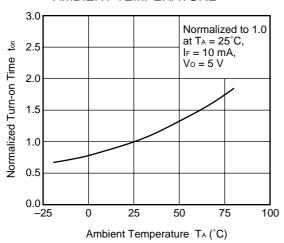
TURN-ON TIME DISTRIBUTION



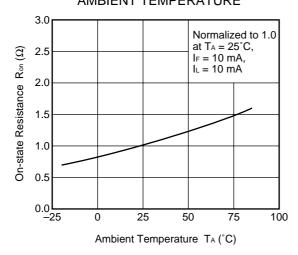
TURN-OFF TIME vs. FORWARD CURRENT



NORMALIZED TURN-ON TIME vs. AMBIENT TEMPERATURE

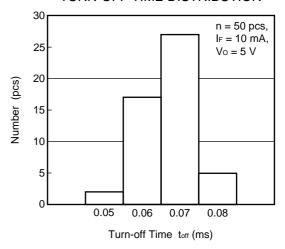


ON-STATE RESISTANCE vs. AMBIENT TEMPERATURE

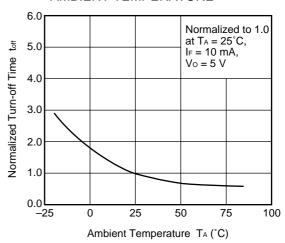


Remark The graphs indicate nominal characteristics.

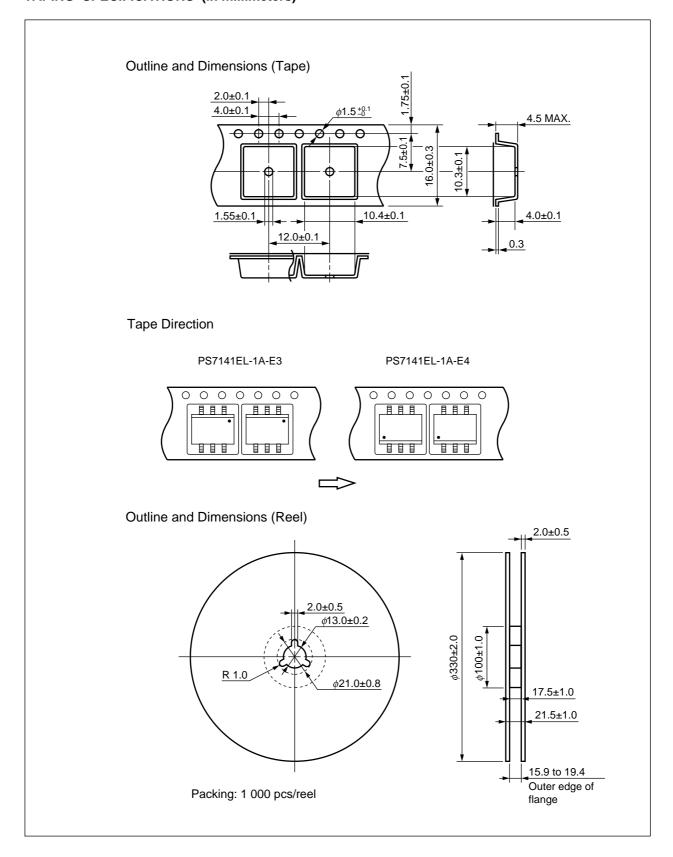
TURN-OFF TIME DISTRIBUTION



NORMALIZED TURN-OFF TIME vs. AMBIENT TEMPERATURE



TAPING SPECIFICATIONS (in millimeters)



RECOMMENDED SOLDERING CONDITIONS

(1) Infrared reflow soldering

• Peak reflow temperature 260°C or below (package surface temperature)

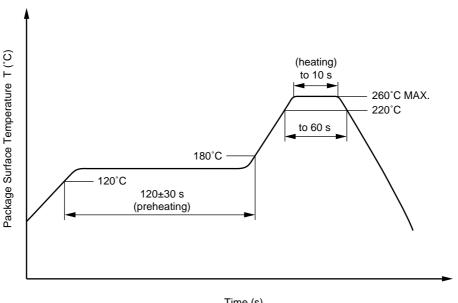
• Time of peak reflow temperature 10 seconds or less • Time of temperature higher than 220°C 60 seconds or less

• Time to preheat temperature from 120 to 180°C 120±30 s • Number of reflows Three

• Flux Rosin flux containing small amount of chlorine (The flux with a

maximum chlorine content of 0.2 Wt% is recommended.)

Recommended Temperature Profile of Infrared Reflow



Time (s)

(2) Wave soldering

• Temperature 260°C or below (molten solder temperature)

• Time 10 seconds or less

· Preheating conditions 120°C or below (package surface temperature)

· Number of times

• Flux Rosin flux containing small amount of chlorine (The flux with a maximum chlorine

content of 0.2 Wt% is recommended.)

(3) Cautions

Fluxes

Avoid removing the residual flux with freon-based and chlorine-based cleaning solvent.

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M8E 00.4-0110

Caution

GaAs Products

This product uses gallium arsenide (GaAs).

GaAs vapor and powder are hazardous to human health if inhaled or ingested, so please observe the following points.

- Follow related laws and ordinances when disposing of the product. If there are no applicable laws and/or ordinances, dispose of the product as recommended below.
 - Commission a disposal company able to (with a license to) collect, transport and dispose of materials that contain arsenic and other such industrial waste materials.
 - 2. Exclude the product from general industrial waste and household garbage, and ensure that the product is controlled (as industrial waste subject to special control) up until final disposal.
- Do not burn, destroy, cut, crush, or chemically dissolve the product.
- Do not lick the product or in any way allow it to enter the mouth.

▶ For further information, please contact

NEC Compound Semiconductor Devices, Ltd. http://www.ncsd.necel.com/

E-mail: salesinfo@csd-nec.com (sales and general) techinfo@csd-nec.com (technical)

5th Sales Group, Sales Division TEL: +81-44-435-1588 FAX: +81-44-435-1579

NEC Compound Semiconductor Devices Hong Kong Limited

E-mail: ncsd-hk@elhk.nec.com.hk (sales, technical and general)

Hong Kong Head Office TEL: +852-3107-7303 FAX: +852-3107-7309
Taipei Branch Office TEL: +886-2-8712-0478 FAX: +886-2-2545-3859
Korea Branch Office TEL: +82-2-558-2120 FAX: +82-2-558-5209

NEC Electronics (Europe) GmbH http://www.ee.nec.de/

TEL: +49-211-6503-01 FAX: +49-211-6503-487

California Eastern Laboratories, Inc. http://www.cel.com/

TEL: +1-408-988-3500 FAX: +1-408-988-0279